Data sheet acquired from Harris Semiconductor
SCHS047G

August 1998 - Revised October 2003

Features

- Wide Range of Digital and Analog Signal Levels
  - Digital . . . . . 3V to 20V
  - Analog . . . . . $\leq 20V_{P-P}$
- Low ON Resistance, 125Ω (Typ) Over $15V_{P-P}$ Signal Input Range for V_{DD}-V_{EE} = 18V
- High OFF Resistance, Channel Leakage of ±100pA (Typ) at V_{DD}-V_{EE} = 18V
- Logic-Level Conversion for Digital Addressing Signals of 3V to 20V (V_{DD}-V_{SS} = 3V to 20V) to Switch Analog Signals to $20V_{P-P}$ (V_{DD}-V_{EE} = 20V)
- Matched Switch Characteristics, r_{ON} = 5Ω (Typ) for V_{DD}-V_{EE} = 15V
- Very Low Quiescent Power Dissipation Under All Digital-Control Input and Supply Conditions, 0.2μW (Typ) at V_{DD}-V_{SS} = V_{DD}-V_{EE} = 10V
- Binary Address Decoding on Chip
- 5V, 10V, and 15V Parametric Ratings
- 100% Tested for Quiescent Current at 20V
- Maximum Input Current of 1μA at 18V Over Full Package Temperature Range, 100nA at 18V and 25°C
- Break-Before-Make Switching Eliminates Channel Overlap

Applications

- Analog and Digital Multiplexing and Demultiplexing
- A/D and D/A Conversion
- Signal Gating

CMOS Analog Multiplexers/Demultiplexers with Logic Level Conversion

The CD4051B, CD4052B, and CD4053B analog multiplexers are digitally-controlled analog switches having low ON impedance and very low OFF leakage current. Control of analog signals up to $20V_{P-P}$ can be achieved by digital signal amplitudes of 4.5V to 20V (if V_{DD}-V_{SS} = 3V, a V_{DD}-V_{EE} of up to 13V can be controlled; for V_{DD}-V_{EE} level differences above 13V, a V_{DD}-V_{SS} of at least 4.5V is required). For example, if V_{DD} = +4.5V, V_{SS} = 0V, and V_{EE} = -13.5V, analog signals from -13.5V to +4.5V can be controlled by digital inputs of 0V to 5V. These multiplexer circuits dissipate extremely low quiescent power over the full V_{DD}-V_{SS} and V_{DD}-V_{EE} supply-voltage ranges, independent of the logic state of the control signals. When a logic "1" is present at the inhibit input terminal, all channels are off.

The CD4051B is a single 8-Channel multiplexer having three binary control inputs, A, B, and C, and an inhibit input. The three binary signals select 1 of 8 channels to be turned on, and connect one of the 8 inputs to the output.

The CD4052B is a differential 4-Channel multiplexer having two binary control inputs, A and B, and an inhibit input. The two binary input signals select 1 of 4 pairs of channels to be turned on and connect the analog inputs to the outputs.

The CD4053B is a triple 2-Channel multiplexer having three separate digital control inputs, A, B, and C, and an inhibit input. Each control input selects one of a pair of channels which are connected in a single-pole, double-throw configuration.

When these devices are used as demultiplexers, the "CHANNEL IN/OUT" terminals are the outputs and the "COMMON OUT/IN" terminals are the inputs.

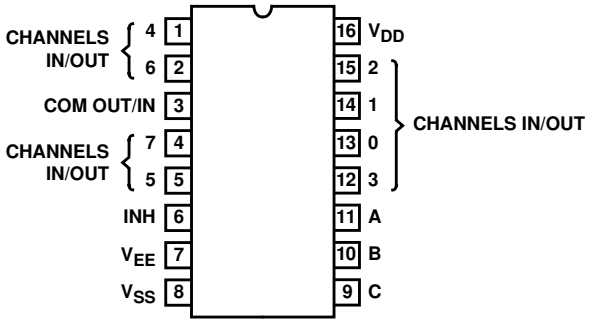
Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD4051BF3A, CD4052BF3A, CD4053BF3A	-55 to 125	16 Ld CERAMIC DIP
CD4051BE, CD4052BE, CD4053BE	-55 to 125	16 Ld PDIP
CD4051BM, CD4051BMT, CD4051BM96 CD4052BM, CD4052BMT, CD4052BM96 CD4053BM, CD4053BMT, CD4053BM96	-55 to 125	16 Ld SOIC
CD4051BNSR, CD4052BNSR, CD4053BNSR	-55 to 125	16 Ld SOP
CD4051BPW, CD4051BPWR, CD4052BPW, CD4052BPWR CD4053BPW, CD4053BPWR	-55 to 125	16 Ld TSSOP

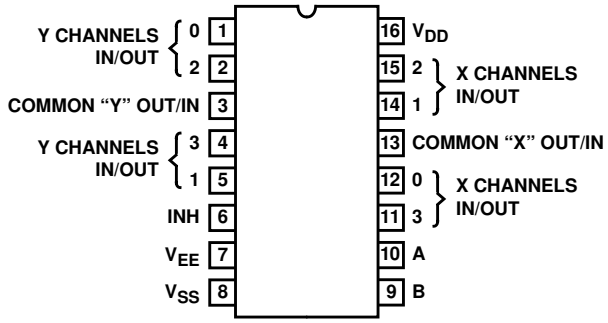
NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel. The suffix T denotes a small-quantity reel of 250.

Pinouts

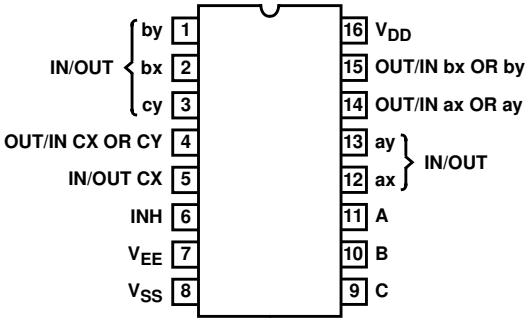
CD4051B (PDIP, CDIP, SOIC, SOP, TSSOP)
TOP VIEW



CD4052B (PDIP, CDIP, SOP, TSSOP)
TOP VIEW

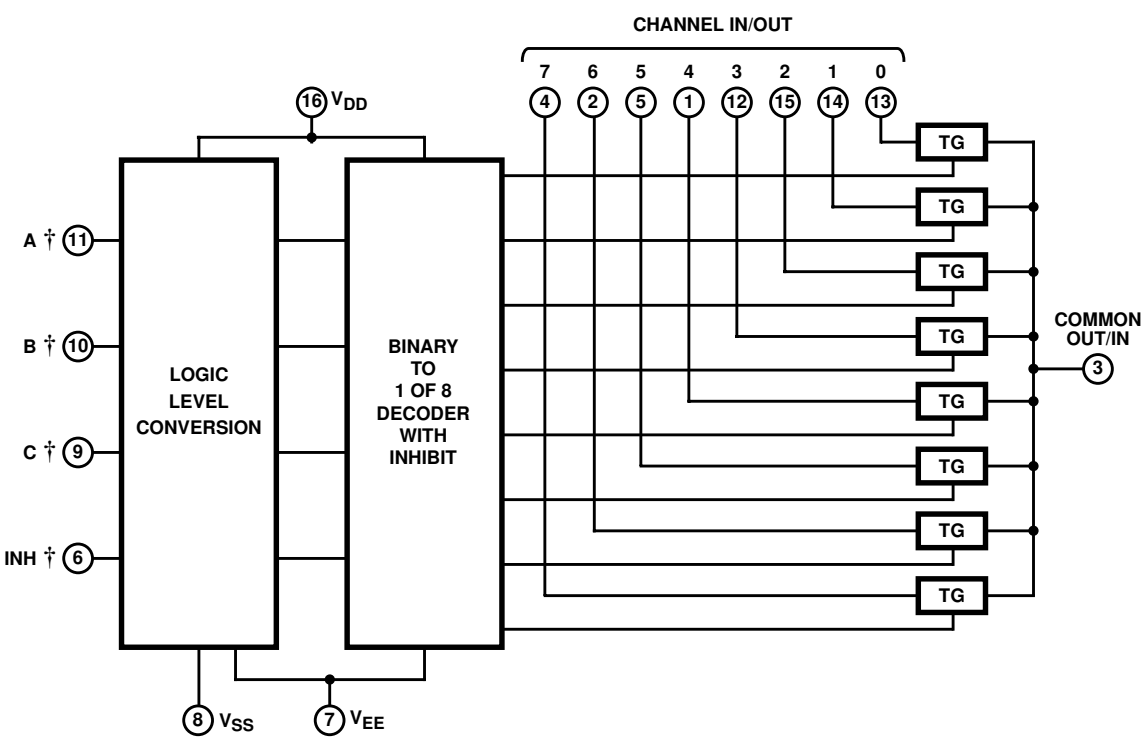


CD4053B (PDIP, CDIP, SOP, TSSOP)
TOP VIEW



Functional Block Diagrams

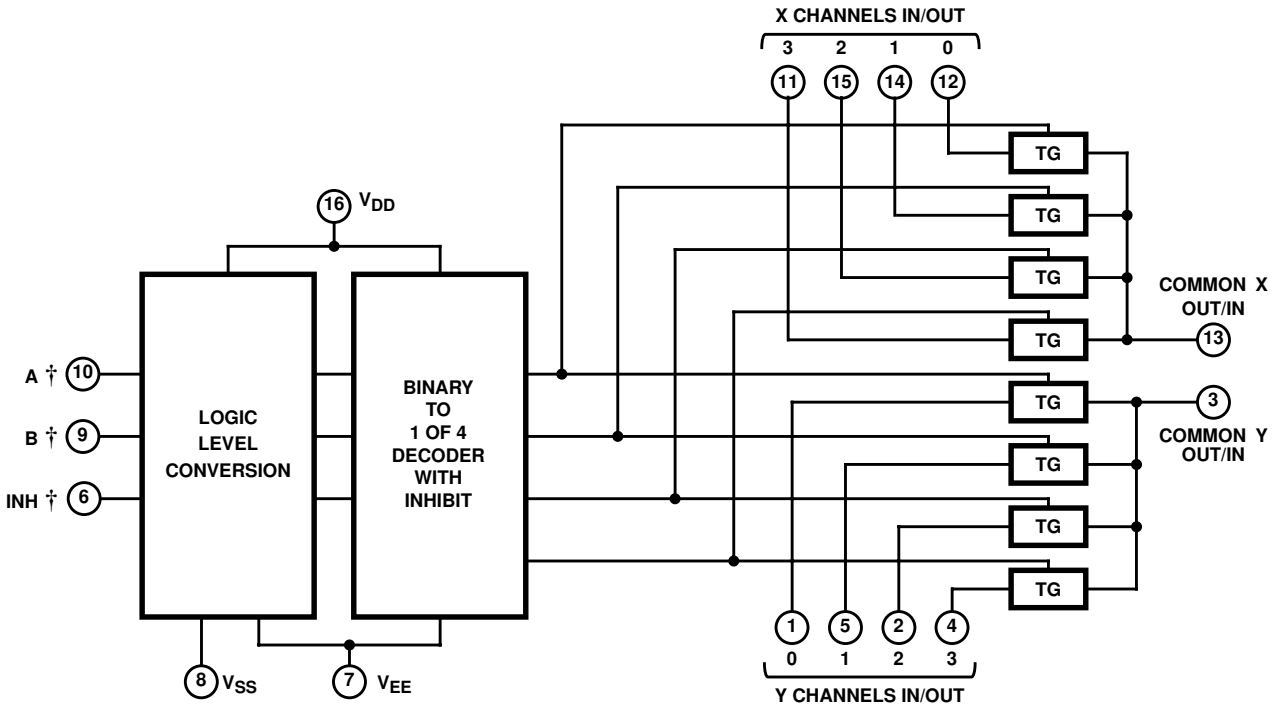
CD4051B



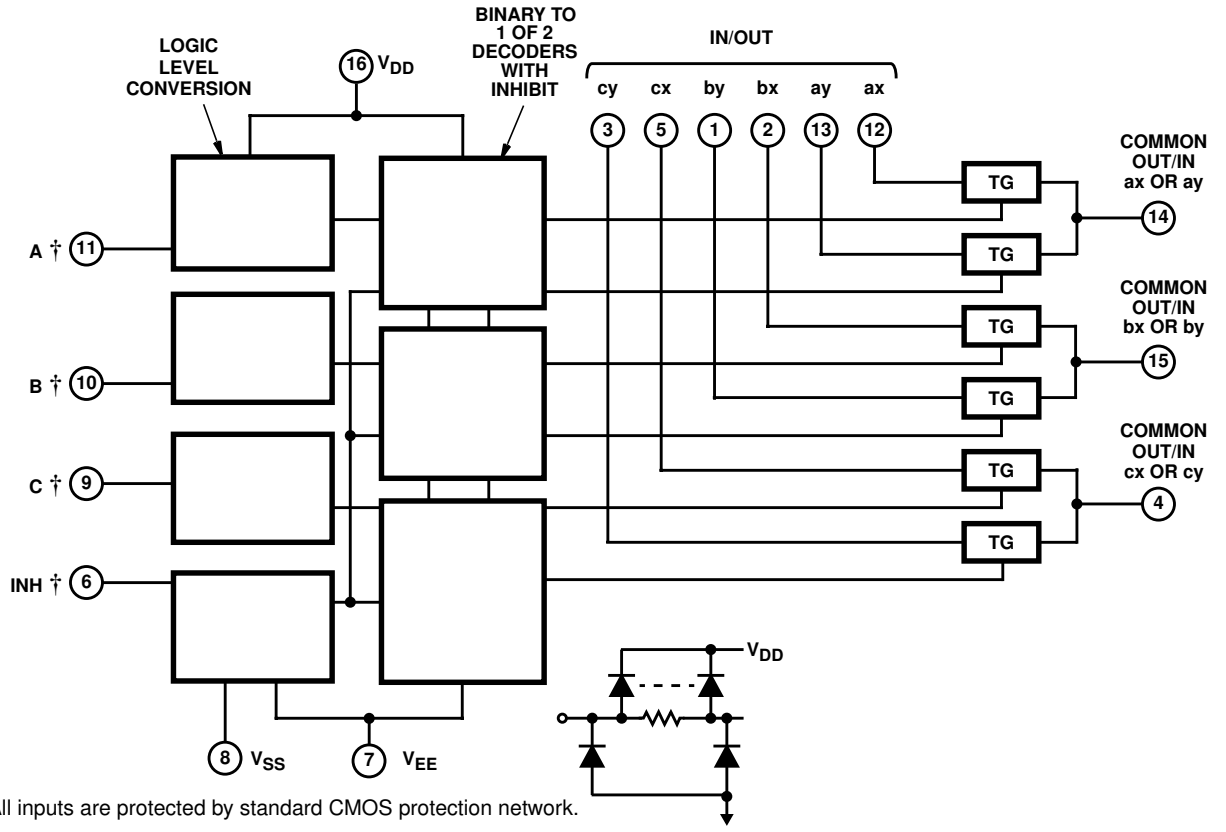
† All inputs are protected by standard CMOS protection network.

Functional Block Diagrams (Continued)

CD4052B



CD4053B



† All inputs are protected by standard CMOS protection network.

TRUTH TABLES

INPUT STATES				
INHIBIT	**C**	**B**	**A**	**"ON" CHANNEL(S)**
CD4051B				
0	0	0	0	0
0	0	0	1	1
0	0	1	0	2
0	0	1	1	3
0	1	0	0	4
0	1	0	1	5
0	1	1	0	6
0	1	1	1	7
1	X	X	X	None
CD4052B				
INHIBIT	**B**		**A**	
0	0		0	0x, 0y
0	0		1	1x, 1y
0	1		0	2x, 2y
0	1		1	3x, 3y
1	X		X	None
CD4053B				
INHIBIT	**A OR B OR C**			
0	0			ax or bx or cx
0	1			ay or by or cy
1	X			None

X = Don't Care

Absolute Maximum Ratings

Supply Voltage (V+ to V-)
Voltages Referenced to V_{SS} Terminal . . . . . -0.5V to 20V
DC Input Voltage Range . . . . . -0.5V to V_{DD} +0.5V
DC Input Current, Any One Input. . . . . ±10mA

Operating Conditions

Temperature Range . . . . . -55°C to 125°C

Thermal Information

Package Thermal Impedance, θ_{JA} (see Note 1):
E (PDIP) package. . . . . 67°C/W
M (SOIC) package . . . . . 73°C/W
NS (SOP) package. . . . . 64°C/W
PW (TSSOP) package . . . . . 108°C/W
Maximum Junction Temperature (Ceramic Package) . . . . . .175°C
Maximum Junction Temperature (Plastic Package) . . . . . .150°C
Maximum Storage Temperature Range. . . . . -65°C to 150°C
Maximum Lead Temperature (Soldering 10s) . . . . . .265°C
(SOIC - Lead Tips Only)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

Electrical Specifications

Common Conditions Here: If Whole Table is For the Full Temp. Range, V_{SUPPLY} = ±5V, A_V = +1, R_L = 100Ω, Unless Otherwise Specified (Note 3)

PARAMETER	CONDITIONS				LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
									25			
	V_{IS} (V)	V_{EE} (V)	V_{SS} (V)	V_{DD} (V)	-55	-40	85	125	MIN	TYP	MAX	
SIGNAL INPUTS (V_{IS}) AND OUTPUTS (V_{OS})												
Quiescent Device Current, I_{DD} Max	-	-	-	5	5	5	150	150	-	0.04	5	µA
	-	-	-	10	10	10	300	300	-	0.04	10	µA
	-	-	-	15	20	20	600	600	-	0.04	20	µA
	-	-	-	20	100	100	3000	3000	-	0.08	100	µA
Drain to Source ON Resistance r_{ON} Max $0 \le V_{IS} \le V_{DD}$	-	0	0	5	800	850	1200	1300	-	470	1050	Ω
	-	0	0	10	310	330	520	550	-	180	400	Ω
	-	0	0	15	200	210	300	320	-	125	240	Ω
Change in ON Resistance (Between Any Two Channels), Δr_{ON}	-	0	0	5	-	-	-	-	-	15	-	Ω
	-	0	0	10	-	-	-	-	-	10	-	Ω
	-	0	0	15	-	-	-	-	-	5	-	Ω
OFF Channel Leakage Current: Any Channel OFF (Max) or ALL Channels OFF (Common OUT/IN) (Max)	-	0	0	18	±100 (Note 2)		±1000 (Note 2)		-	±0.01	±100 (Note 2)	nA
Capacitance:	-	-5	5-	5								
Input, C_{IS}					-	-	-	-	-	5	-	pF
Output, C_{OS}												
CD4051					-	-	-	-	-	30	-	pF
CD4052					-	-	-	-	-	18	-	pF
CD4053					-	-	-	-	-	9	-	pF
Feedthrough C_{IOS}					-	-	-	-	-	0.2	-	pF
Propagation Delay Time (Signal Input to Output	V_{DD} 	R_L = 200kΩ, C_L = 50pF, t_r, t_f = 20ns		5	-	-	-	-	-	30	60	ns
				10	-	-	-	-	-	15	30	ns
				15	-	-	-	-	-	10	20	ns

Electrical Specifications

Common Conditions Here: If Whole Table is For the Full Temp. Range, V_{SUPPLY} = ±5V, A_V = +1, R_L = 100Ω, Unless Otherwise Specified **(Continued)** (Note 3)

PARAMETER	CONDITIONS				LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
									25			
	V_{IS} (V)	V_{EE} (V)	V_{SS} (V)	V_{DD} (V)	-55	-40	85	125	MIN	TYP	MAX	
CONTROL (ADDRESS OR INHIBIT), V_C												
Input Low Voltage, V_{IL}, Max	V_{IL} = V_{DD} through 1kΩ; V_{IH} = V_{DD} through 1kΩ	V_{EE} = V_{SS}, R_L = 1kΩ to V_{SS}, I_{IS} < 2μA on All OFF Channels		5	1.5	1.5	1.5	1.5	-	-	1.5	V
				10	3	3	3	3	-	-	3	V
				15	4	4	4	4	-	-	4	V
Input High Voltage, V_{IH}, Min				5	3.5	3.5	3.5	3.5	3.5	-	-	V
				10	7	7	7	7	7	-	-	V
				15	11	11	11	11	11	-	-	V
Input Current, I_{IN} (Max)	V_{IN} = 0, 18			18	±0.1	±0.1	±1	±1	-	$\pm 10^{-5}$	±0.1	μA
Propagation Delay Time: Address-to-Signal OUT (Channels ON or OFF) See Figures 10, 11, 14	t_r, t_f = 20ns, C_L = 50pF, R_L = 10kΩ	0	0	5	-	-	-	-	-	450	720	ns
		0	0	10	-	-	-	-	-	160	320	ns
		0	0	15	-	-	-	-	-	120	240	ns
		-5	0	5	-	-	-	-	-	225	450	ns
Propagation Delay Time: Inhibit-to-Signal OUT (Channel Turning ON) See Figure 11	t_r, t_f = 20ns, C_L = 50pF, R_L = 1kΩ	0	0	5	-	-	-	-	-	400	720	ns
		0	0	10	-	-	-	-	-	160	320	ns
		0	0	15	-	-	-	-	-	120	240	ns
		-10	0	5	-	-	-	-	-	200	400	ns
Propagation Delay Time: Inhibit-to-Signal OUT (Channel Turning OFF) See Figure 15	t_r, t_f = 20ns, C_L = 50pF, R_L = 10kΩ	0	0	5	-	-	-	-	-	200	450	ns
		0	0	10	-	-	-	-	-	90	210	ns
		0	0	15	-	-	-	-	-	70	160	ns
		-10	0	5	-	-	-	-	-	130	300	ns
Input Capacitance, C_{IN} (Any Address or Inhibit Input)					-	-	-	-	-	5	7.5	pF

NOTE:

2. Determined by minimum feasible leakage measurement for automatic testing.

Electrical Specifications

PARAMETER	TEST CONDITIONS					LIMITS	UNITS
	V_{IS} (V)	V_{DD} (V)	R_L (kΩ)			TYP	
Cutoff (-3dB) Frequency Channel ON (Sine Wave Input)	5 (Note 3)	10	1	V_{OS} at Common OUT/IN	CD4053	30	MHz
	V_{EE} = V_{SS}, $20\text{Log}\frac{V_{OS}}{V_{IS}} = -3\text{dB}$				CD4052	25	MHz
					CD4051	20	MHz
				V_{OS} at Any Channel		60	MHz

Electrical Specifications

PARAMETER	TEST CONDITIONS					LIMITS	UNITS
	V_{IS} (V)	V_{DD} (V)	R_L (kΩ)			TYP	
Total Harmonic Distortion, THD	2 (Note 3)	5	10			0.3	%
	3 (Note 3)	10				0.2	%
	5 (Note 3)	15				0.12	%
	$V_{EE} = V_{SS}$, f_{IS} = 1kHz Sine Wave						%
-40dB Feedthrough Frequency (All Channels OFF)	5 (Note 3)	10	1	V_{OS} at Common OUT/IN	CD4053	8	MHz
	$V_{EE} = V_{SS}$, $20\text{Log}\frac{V_{OS}}{V_{IS}} = -40\text{dB}$				CD4052	10	MHz
					CD4051	12	MHz
				V_{OS} at Any Channel		8	MHz
-40dB Signal Crosstalk Frequency	5 (Note 3)	10	1	Between Any 2 Channels		3	MHz
	$V_{EE} = V_{SS}$, $20\text{Log}\frac{V_{OS}}{V_{IS}} = -40\text{dB}$			Between Sections, CD4052 Only	Measured on Common	6	MHz
					Measured on Any Channel	10	MHz
				Between Any Two Sections, CD4053 Only	In Pin 2, Out Pin 14	2.5	MHz
					In Pin 15, Out Pin 14	6	MHz
Address-or-Inhibit-to-Signal Crosstalk	-	10	10 (Note 4)			65	mV_{PEAK}
	$V_{EE} = 0$, $V_{SS} = 0$, t_r, t_f = 20ns, $V_{CC} = V_{DD} - V_{SS}$ (Square Wave)					65	mV_{PEAK}

NOTES:

3. Peak-to-Peak voltage symmetrical about $\frac{V_{DD} - V_{EE}}{2}$
4. Both ends of channel.

Typical Performance Curves

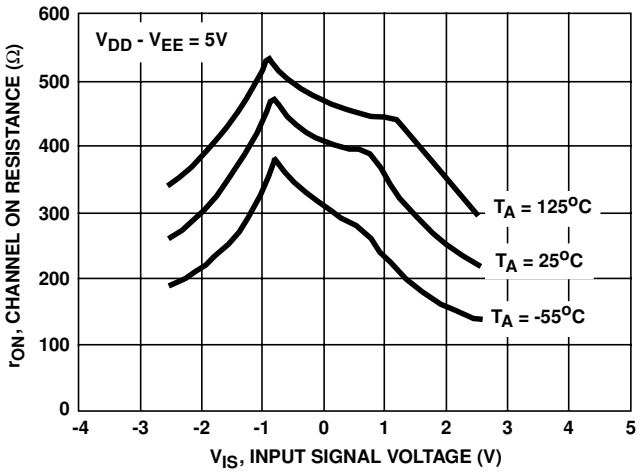


FIGURE 1. CHANNEL ON RESISTANCE vs INPUT SIGNAL VOLTAGE (ALL TYPES)

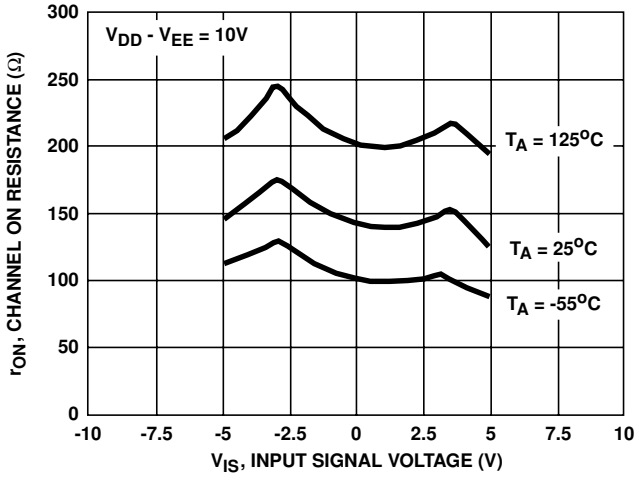


FIGURE 2. CHANNEL ON RESISTANCE vs INPUT SIGNAL VOLTAGE (ALL TYPES)

Typical Performance Curves (Continued)

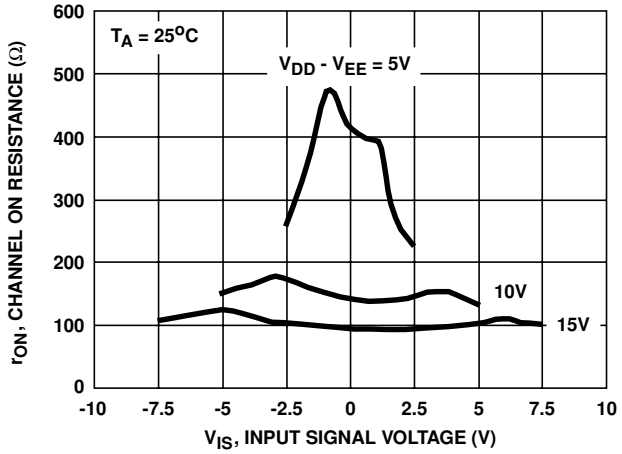


FIGURE 3. CHANNEL ON RESISTANCE vs INPUT SIGNAL VOLTAGE (ALL TYPES)

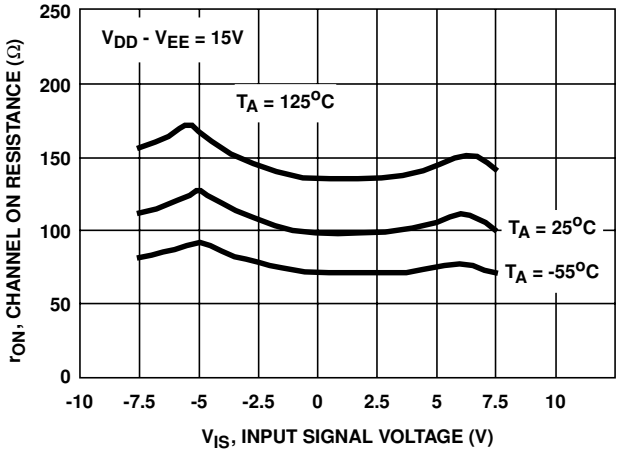


FIGURE 4. CHANNEL ON RESISTANCE vs INPUT SIGNAL VOLTAGE (ALL TYPES)

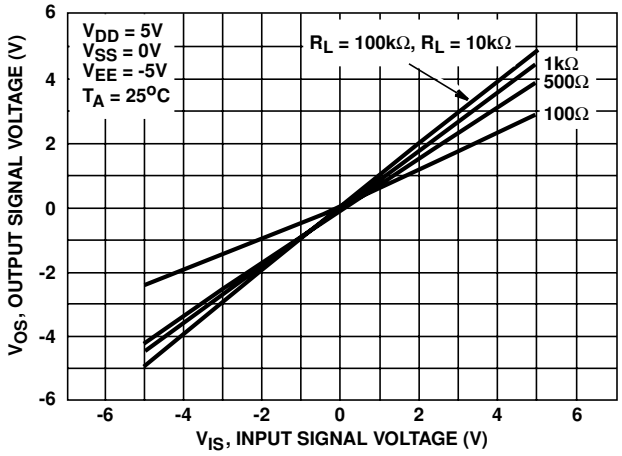


FIGURE 5. ON CHARACTERISTICS FOR 1 OF 8 CHANNELS (CD4051B)

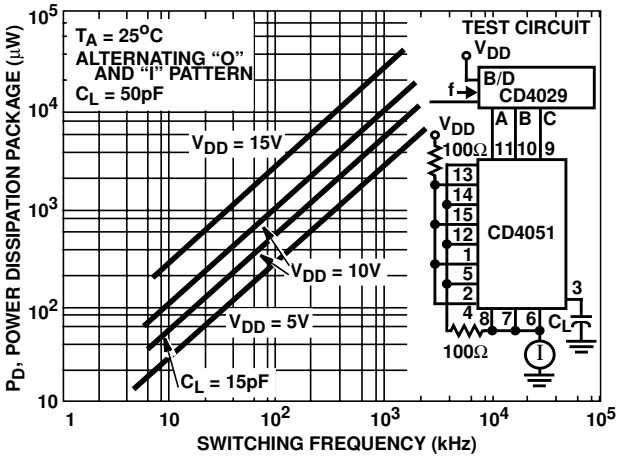


FIGURE 6. DYNAMIC POWER DISSIPATION vs SWITCHING FREQUENCY (CD4051B)

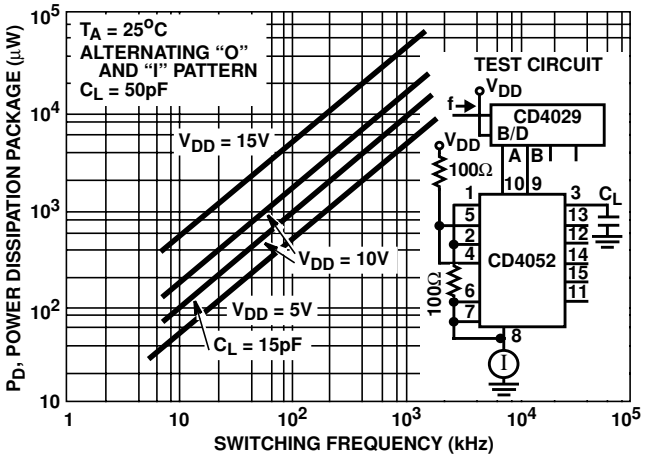


FIGURE 7. DYNAMIC POWER DISSIPATION vs SWITCHING FREQUENCY (CD4052B)

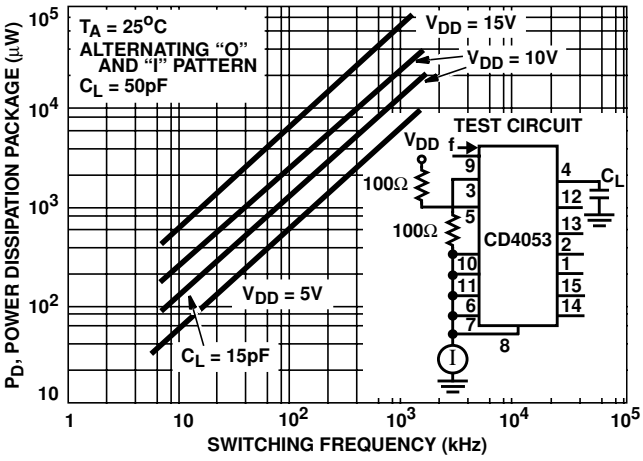
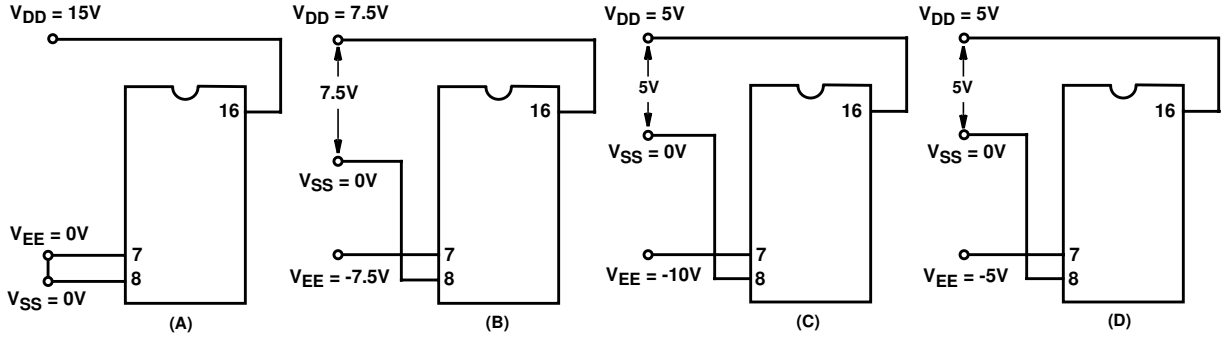


FIGURE 8. DYNAMIC POWER DISSIPATION vs SWITCHING FREQUENCY (CD4053B)

Test Circuits and Waveforms



NOTE: The ADDRESS (digital-control inputs) and INHIBIT logic levels are: "0" = V_{SS} and "1" = V_{DD}. The analog signal (through the TG) may swing from V_{EE} to V_{DD}.

FIGURE 9. TYPICAL BIAS VOLTAGES

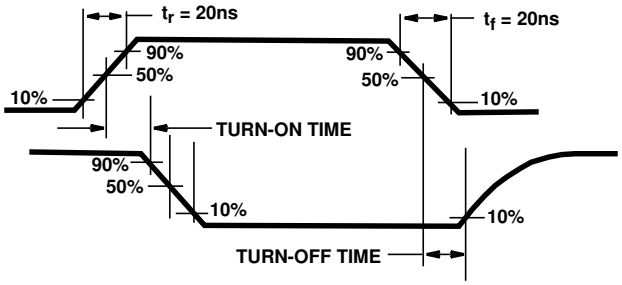


FIGURE 10. WAVEFORMS, CHANNEL BEING TURNED ON (R_L = 1kΩ)

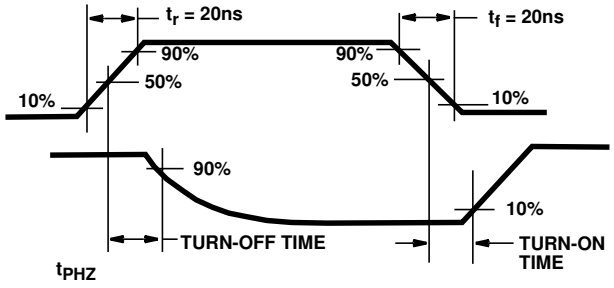


FIGURE 11. WAVEFORMS, CHANNEL BEING TURNED OFF (R_L = 1kΩ)

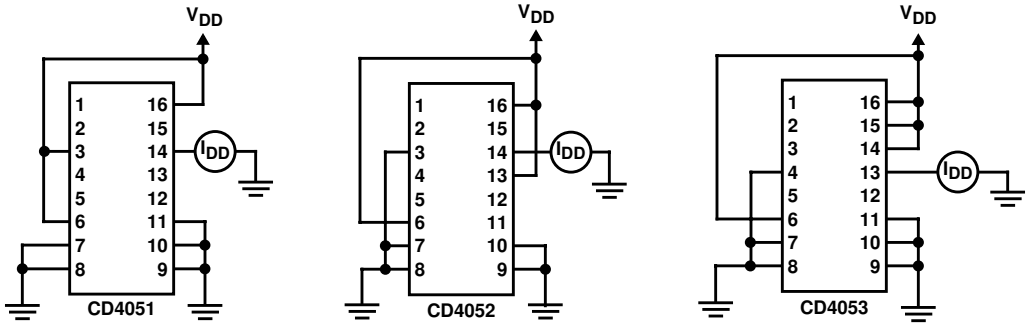


FIGURE 12. OFF CHANNEL LEAKAGE CURRENT - ANY CHANNEL OFF

Test Circuits and Waveforms (Continued)

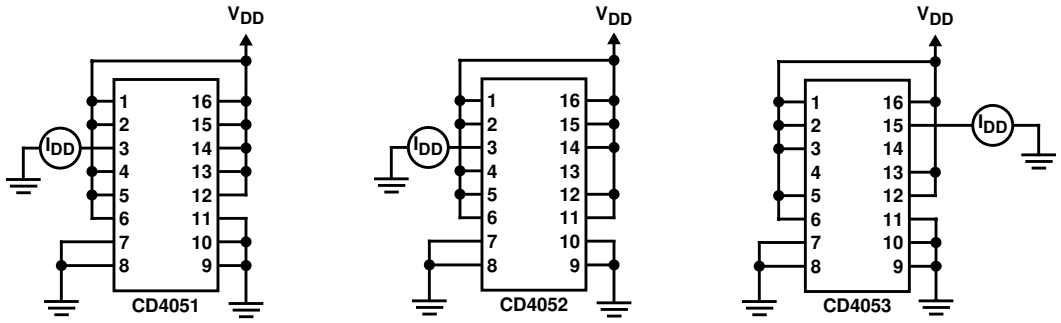


FIGURE 13. OFF CHANNEL LEAKAGE CURRENT - ALL CHANNELS OFF

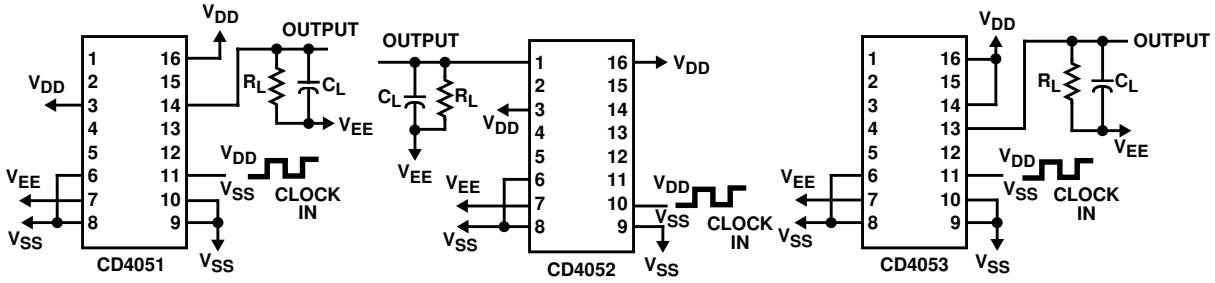


FIGURE 14. PROPAGATION DELAY - ADDRESS INPUT TO SIGNAL OUTPUT

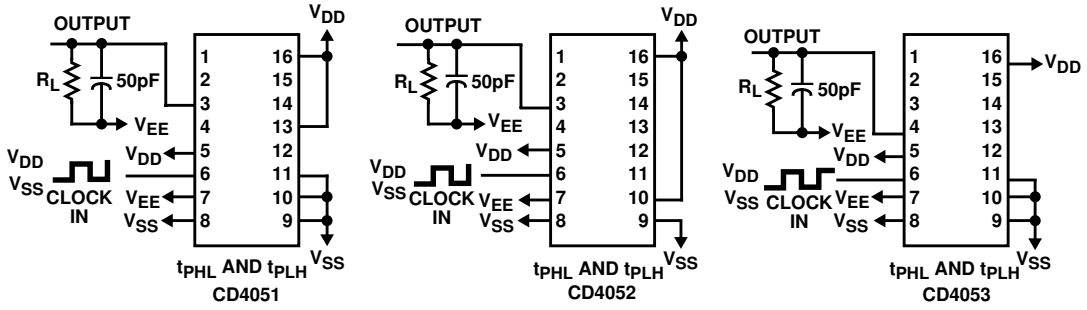


FIGURE 15. PROPAGATION DELAY - INHIBIT INPUT TO SIGNAL OUTPUT

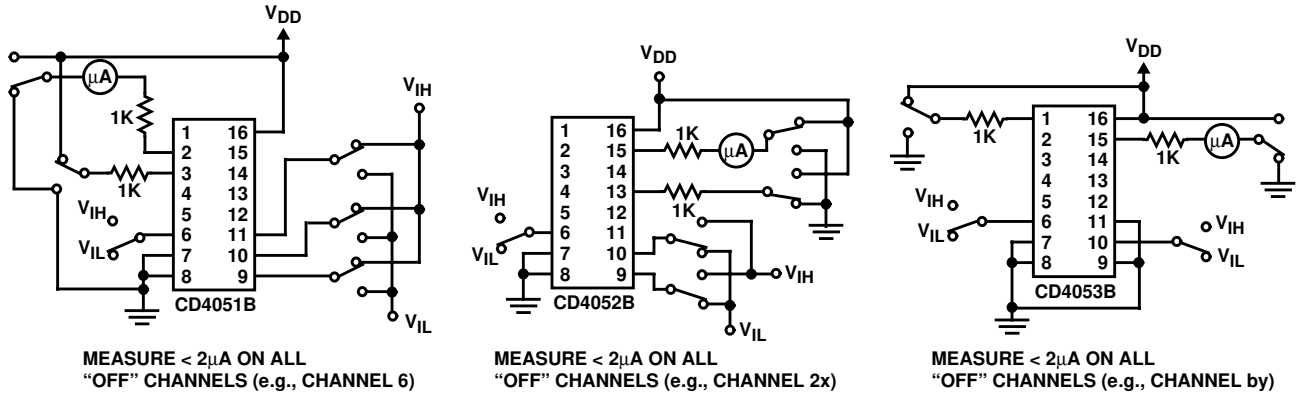


FIGURE 16. INPUT VOLTAGE TEST CIRCUITS (NOISE IMMUNITY)

Test Circuits and Waveforms (Continued)

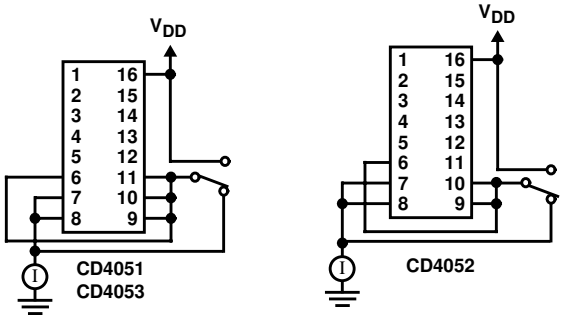


FIGURE 17. QUIESCENT DEVICE CURRENT

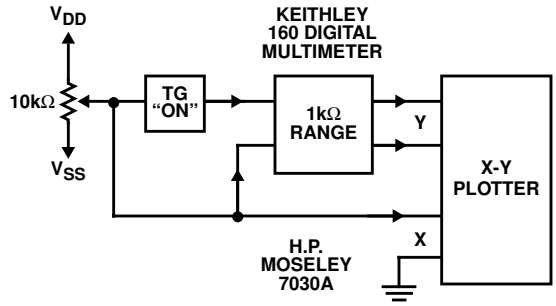


FIGURE 18. CHANNEL ON RESISTANCE MEASUREMENT CIRCUIT

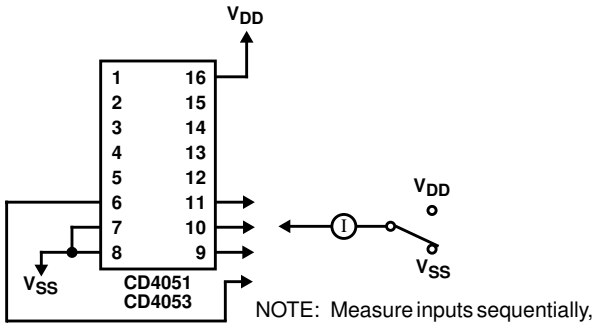


FIGURE 19. INPUT CURRENT

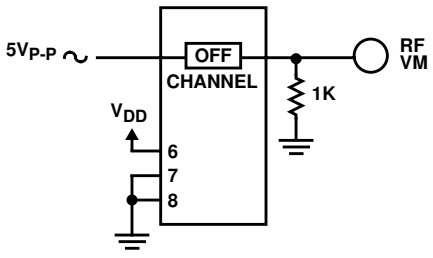


FIGURE 20. FEEDTHROUGH (ALL TYPES)

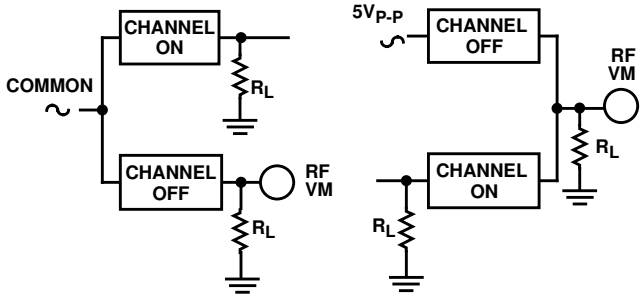


FIGURE 21. CROSSTALK BETWEEN ANY TWO CHANNELS (ALL TYPES)

FIGURE 22. CROSSTALK BETWEEN DUALS OR TRIPLETS (CD4052B, CD4053B)

Test Circuits and Waveforms (Continued)

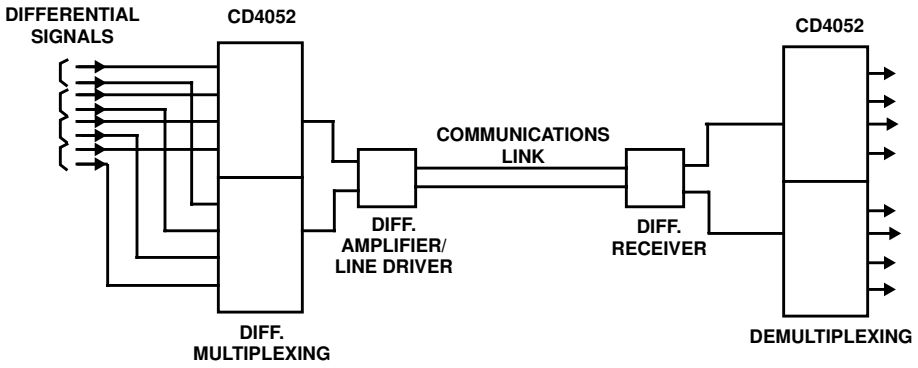


FIGURE 23. TYPICAL TIME-DIVISION APPLICATION OF THE CD4052B

Special Considerations

In applications where separate power sources are used to drive V_{DD} and the signal inputs, the V_{DD} current capability should exceed V_{DD}/R_L (R_L = effective external load). This provision avoids permanent current flow or clamp action on the V_{DD} supply when power is applied or removed from the CD4051B, CD4052B or CD4053B.

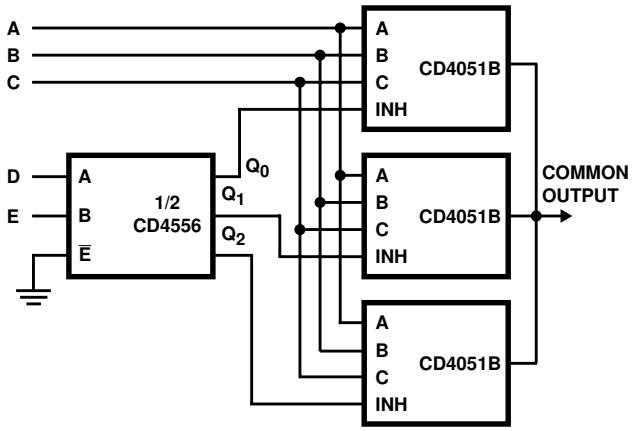


FIGURE 24. 24-TO-1 MUX ADDRESSING

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
7901502EA	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
8101801EA	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4051BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4051BF	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4051BF3A	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4051BM	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
CD4051BM96	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
CD4051BMT	ACTIVE	SOIC	D	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
CD4051BNSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4051BPW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4051BPWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4052BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4052BF	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4052BF3A	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4052BM	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4052BM96	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4052BMT	ACTIVE	SOIC	D	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4052BNSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4052BPW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4052BPWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4053BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4053BF	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4053BF3A	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4053BM	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4053BM96	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4053BMT	ACTIVE	SOIC	D	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4053BNSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4053BPW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
CD4053BPWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

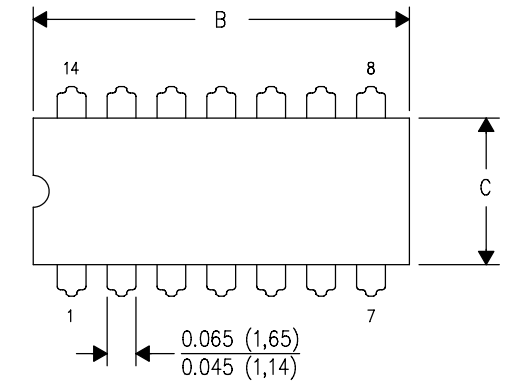
[2] Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
None: Not yet available Lead (Pb-Free).
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

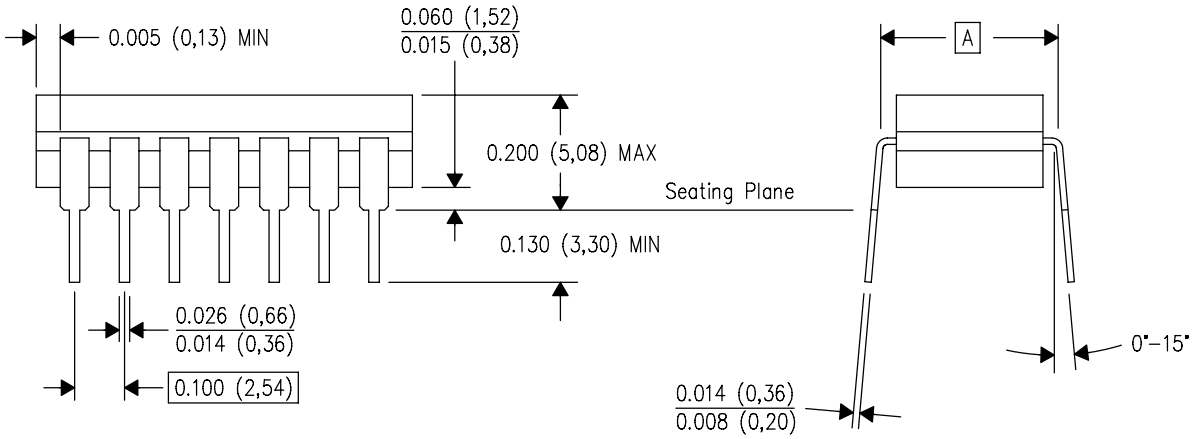
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



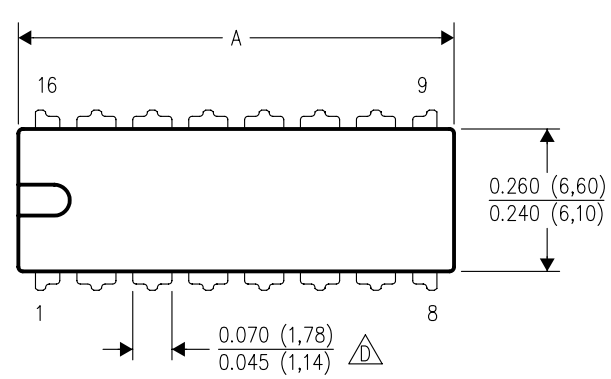
4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

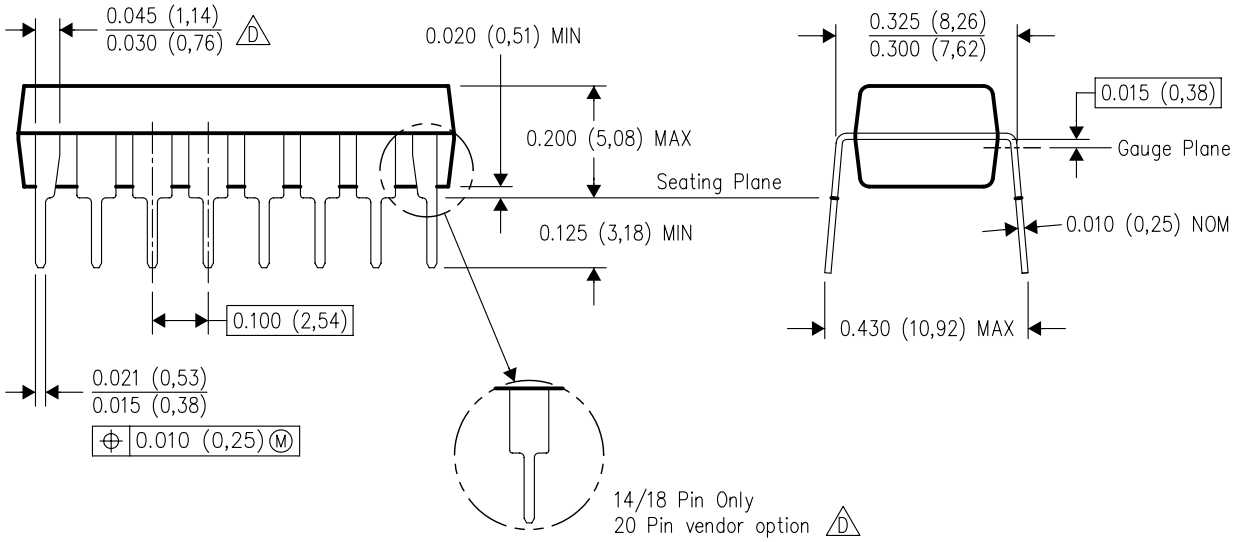
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



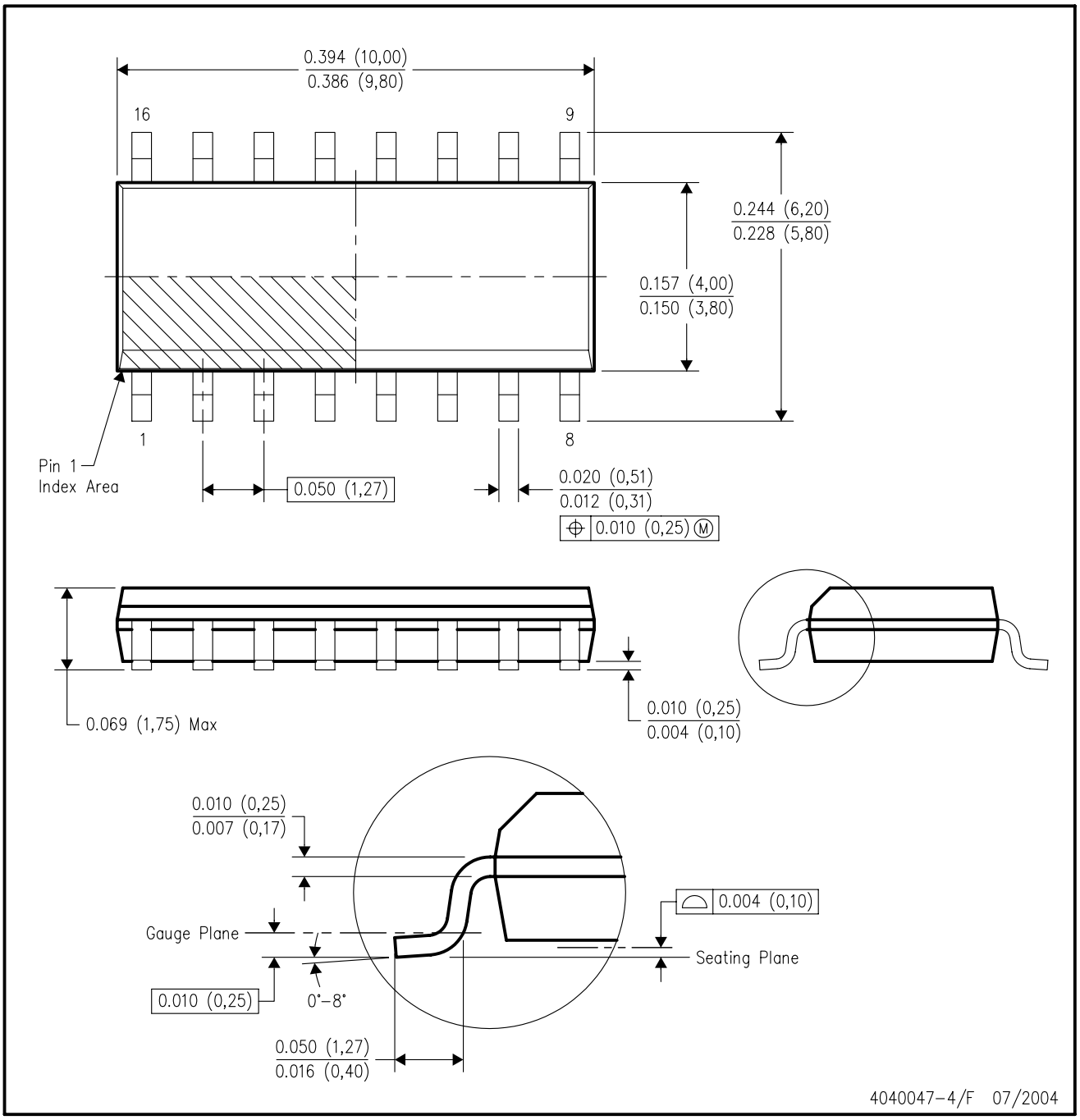
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G16) PLASTIC SMALL–OUTLINE PACKAGE

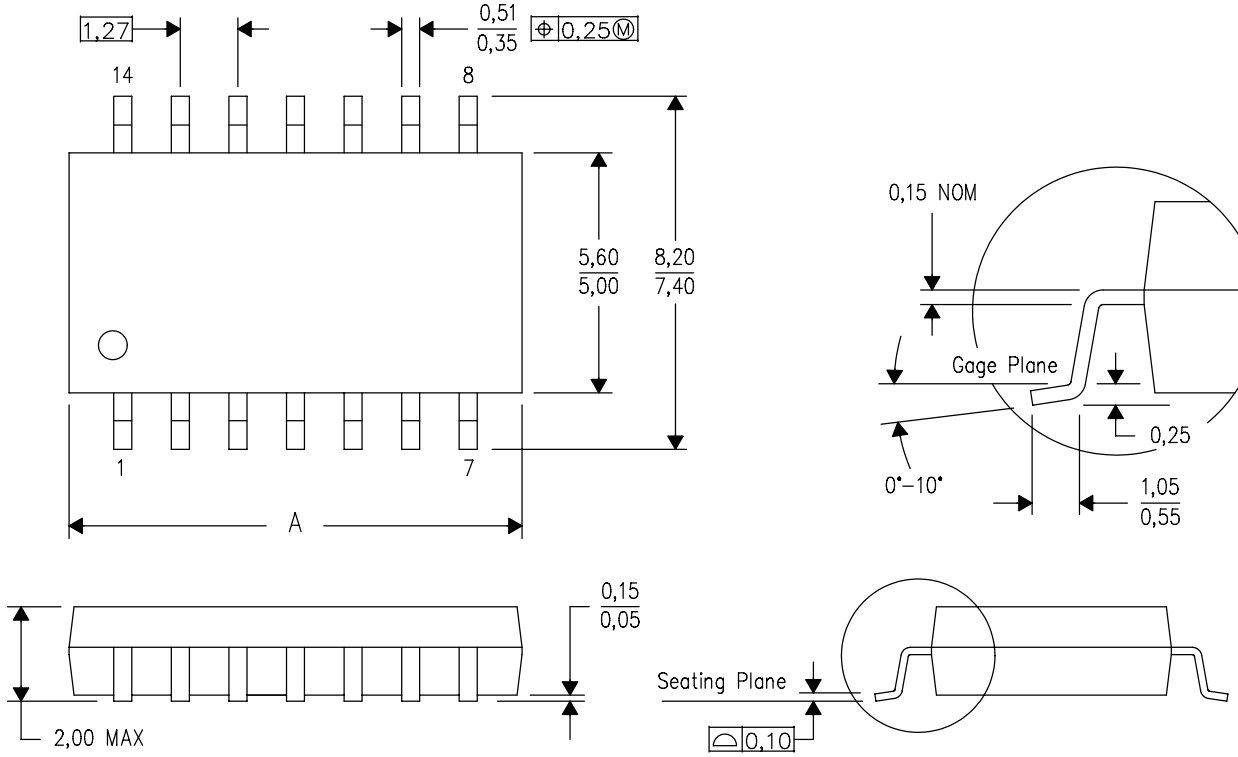


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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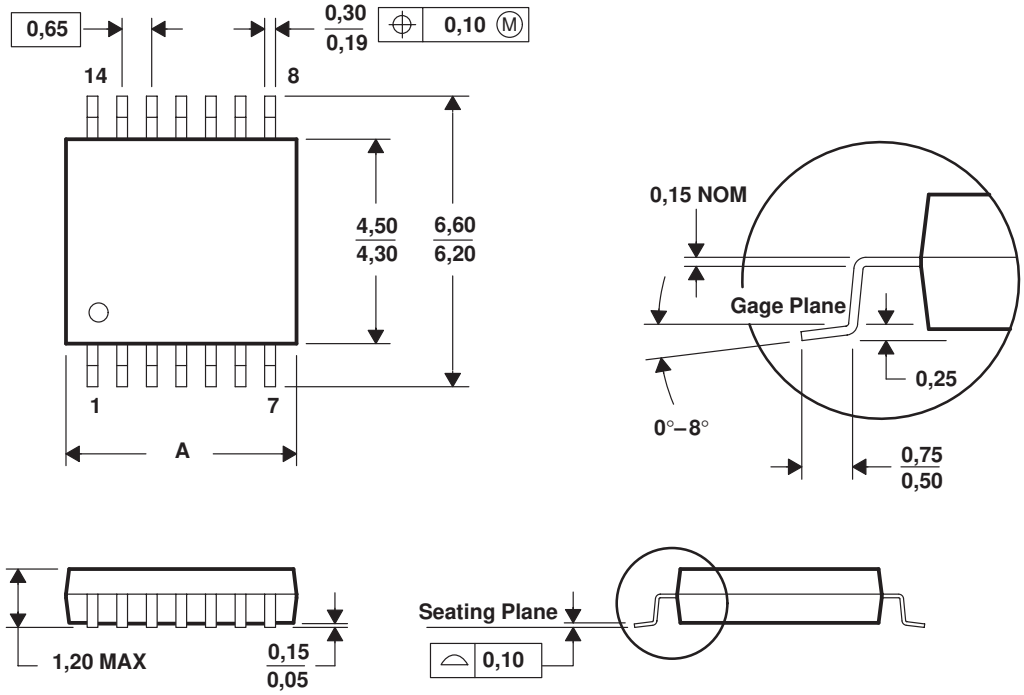
PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN



DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265